Abstract

Due to flip-chip assembling, a surface acoustic wave device can be miniaturized and improved in high frequency characteristics. Despite that, since a resonant system cannot be formed due to an absence of inductance of bonding wire, there is a problem that an attenuation region cannot be disposed in a frequency band apart from the pass band. In order to solve the problem, ground terminal wired to interdigital electrodes of a two-port surface acoustic wave element is extended facing to facing to both output sides of both input and output signal terminals to form capacitance. Due to a resonant system including the capacitance, in a frequency band apart from a pass band of the surface acoustic wave element an attenuation region is formed. Thereby, a surface acoustic wave device that is flexibly adjustable of frequency characteristics in response to system request, can be miniaturized and is improved in characteristics out of band is provided.



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